

## **AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions and listings of claims in the application.

### **COMPLETE LISTING OF CLAIMS:**

Claims 1-11 : (Canceled)

Claim 12 : (New) A method of automatically placing components of a circuit on a base plate based on predefined position data, comprising the steps of:

a) detecting a position of a first reference mark formed at the base plate;  
b) calculating a target position for placing a substrate on the base plate based on the detected position of the first reference mark and the predefined position data, and placing the substrate at the calculated target position;

c) detecting a position of a second reference mark formed at the substrate;  
and

d) calculating a further target position for placing a further component on the substrate based on the detected position of the second reference mark and the predefined position data, and placing the further component at the calculated further target position.

Claim 13 : (New) The method of claim 12, and the step of pressing the further component against an adhesive layer applied to the substrate with a predetermined pressing force and/or duration.

Claim 14 : (New) The method of claim 13, and the step of determining the pressing force and/or duration depending on a shape of the further component.

Claim 15 : (New) The method of claim 12, wherein the step of placing the further component is performed by vertically moving the further component towards the substrate, and decelerating the further component before reaching a surface of the substrate.

Claim 16 : (New) The method of claim 15, wherein the step of calculating the further target position of the further component is performed in three spatial directions taking account of a thickness of the substrate, and the further component is decelerated before reaching a height of the calculated further target position.

Claim 17 : (New) The method of claim 16, wherein step a) is performed by detecting the positions of at least three first reference marks in all three spatial directions, and calculating a height of the substrate based on the detected positions of the height of the three first reference marks.

Claim 18 : (New) The method of claim 17, wherein the height of the substrate surface is measured at the target position, and the further component is decelerated before reaching the measured height.

Claim 19 : (New) The method according to claim 12, wherein the steps a) to d) are carried out while the base plate is located at a same placing machine.

Claim 20 : (New) The method according to claim 12, wherein the steps a) and b) are carried out at a first placing machine, and wherein the steps c) and d) are carried out at a second placing machine.

Claim 21 : (New) The method according to claim 20, wherein the predefined position data are transferred into all placing machines that carry out the steps a) to d) from a CAD system.

Claim 22 : (New) The method according to claim 12, wherein the components of the circuit are substrates and/or circuit components.